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AMENDMENTS TO THE CLAIMS

Claims 1-5. (Canceled)

6. (Currently amended) A method for testing an optical component, comprising:

verifying a high-speed electrical component to be golden;

connecting the optical component to a high-frequency probe;

connecting the high-frequency probe to a ~~golden~~ the high-speed electrical component;

transmitting a high-speed electrical signal from the ~~golden~~ high-speed electrical component to the optical component; and

identifying a response by the optical component to the high-speed electrical signal.

7. (Original) The method of Claim 6, further comprising evaluating the response by the optical component.

8. (Original) The method of Claim 6, further comprising adjusting the high-speed electrical signal.

9. (Original) The method of Claim 7, wherein the step of evaluating the response by the optical component comprises determining if the optical component responds in substantially the same manner as a golden optical component would respond to a substantially equivalent high-speed electrical signal.

10. (Original) The method of Claim 7, wherein the step of evaluating the response by the optical component comprises comparing if the response is substantially the same as a golden optical component response to a substantially equivalent high-speed electrical signal.

Claims 11-20. (Canceled)

21. (Previously presented) The method of Claim 8, further comprising identifying a response by the optical component to the adjusted high-speed electrical signal.

22. (Previously presented) The method of Claim 21, further comprising evaluating the response by the optical component to the adjusted high-speed electrical signal.

Claims 23-25. (Canceled)

26. (New) The method of Claim 6, wherein verifying the high-speed electrical component to be golden comprises verifying the high-speed electrical component as operating according to product application requirements.
27. (New) The method of Claim 6, wherein the high-speed electrical component is located on an application PCB.
28. (New) An apparatus for testing optical components, comprising:  
a high-frequency probe, adapted to removably connect to an optical component and adapted to removably connect to a high-speed electrical component which has been verified as being golden;  
and  
a holder adapted to support the high-frequency probe in a position to removably connect to the high-speed electrical component and removably connect to the optical component.
29. (New) The apparatus of Claim 28, wherein the holder comprises G10 material.
30. (New) The apparatus of Claim 28, wherein the holder comprises Teflon material.
31. (New) The apparatus of Claim 28, wherein the high-frequency probe is double-spring loaded.
32. (New) The apparatus of Claim 28, wherein the high-frequency probe is single-spring loaded.
33. (New) The apparatus of Claim 28, wherein the high-speed electrical component has been verified as being golden by being verified as operating according to product application requirements.
34. (New) The apparatus of Claim 28, wherein the high-speed electrical component is located on an application PCB.